IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier	r Information														
Company name* Comp				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-04-25			
Contact N	ame	Title - Contact			]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	d Representative*		Title - Representative			]	Phone - Representative*				Email - Representative*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	ate Version Manufacturing Site		ring Site	Weight*		UOM	Unit Type	
		FSQ0565	RQWDTU	650V QR Cntrlr w/swtch			2024-04-25		]	РВВ		2	239.009	mg	Each
Manufa	cturing Proccess Informati	ion													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-0		-STD-020 MSI	L Rating	Peak Process Body Tempera		ly Temperatu	ture Max Time at Peak Tempe		Temperatu	ire Numb	er of Reflow Cyc	eles
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 seco		secono	ls 3					
omments	· · · · · · · · · · · · · · · · · · ·														
or more	information regarding material c	omposition <b>j</b>	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content is the content of	sess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- nce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certification conditions of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.8	mg	Supplier	Silicon (Si)	7440-21-3		9.8	mg
Die Attach Epoxy	0.254	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0076	mg
			Supplier	Miscellaneous	Trade Secret		0.0127	mg
			Supplier	Silver (Ag)	7440-22-4		0.2159	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0178	mg
Die Attach Solder	3.061	mg	Supplier	Silver (Ag)	7440-22-4		0.0765	mg
			A	Lead (Pb)	7439-92-1	7a	2.8314	mg
			Supplier	Tin (Sn)	7440-31-5		0.1531	mg
Lead Frame	1264.59	mg	Supplier	Silver (Ag)	7440-22-4		2.91	mg
			Supplier	Tin (Sn)	7440-31-5		1.55	mg
			Supplier	Copper (Cu)	7440-50-8		1260.0045	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1255	mg
Mold Compound-Black	950.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		114	mg
			Supplier	Carbon Black (C)	1333-86-4		4.75	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		831.25	mg
Plating	11.0	mg	Supplier	Tin (Sn)	7440-31-5		11	mg
Wire Bond - Cu	0.304	mg	Supplier	Copper (Cu)	7440-50-8		0.304	mg